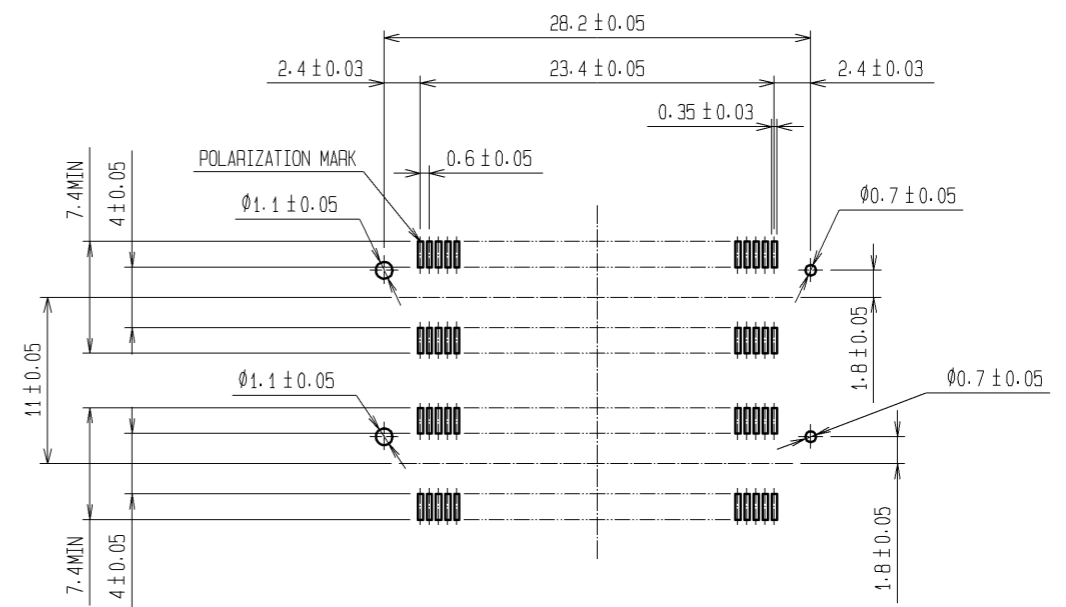


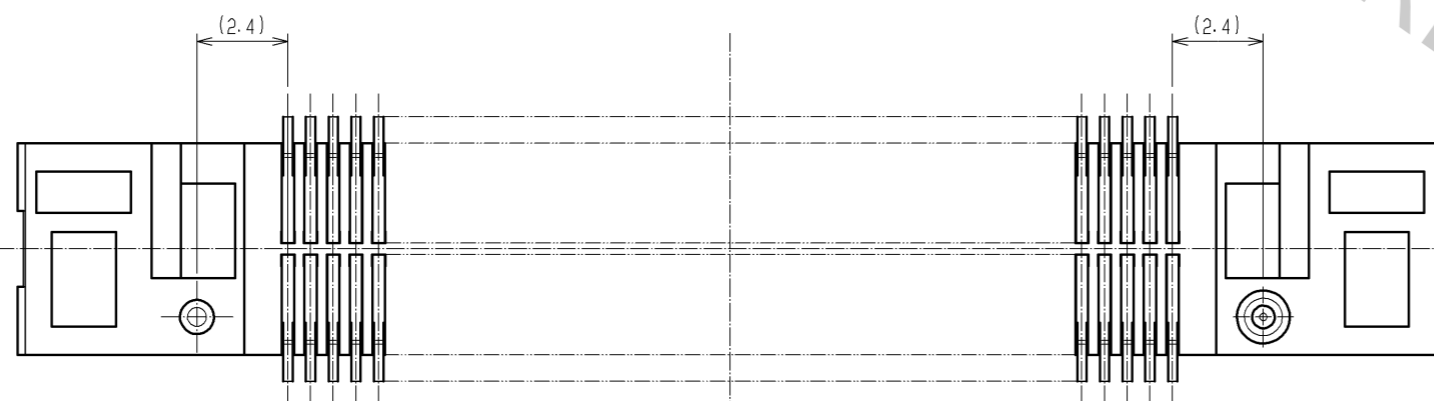
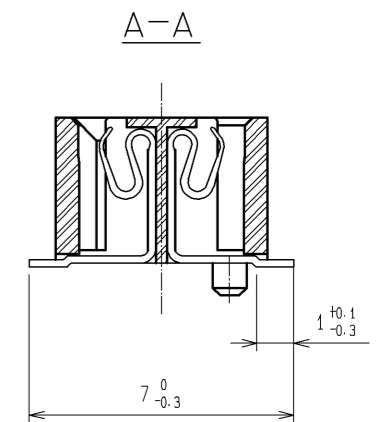
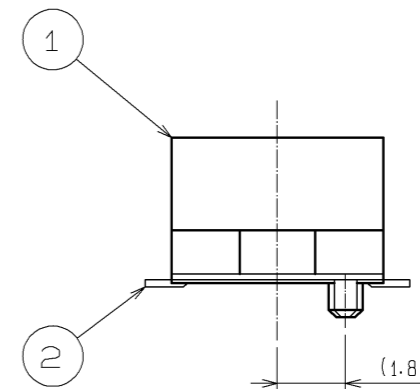
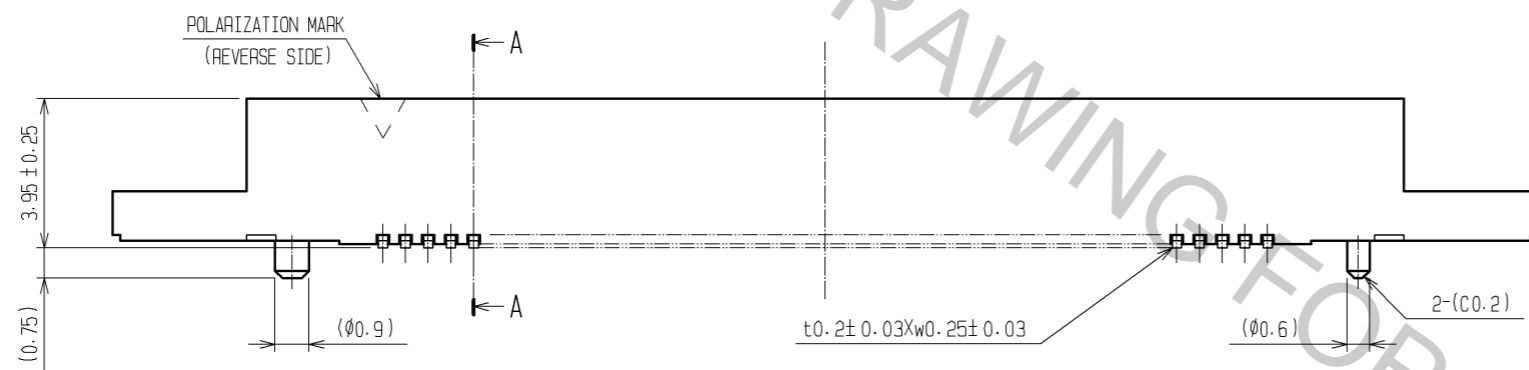
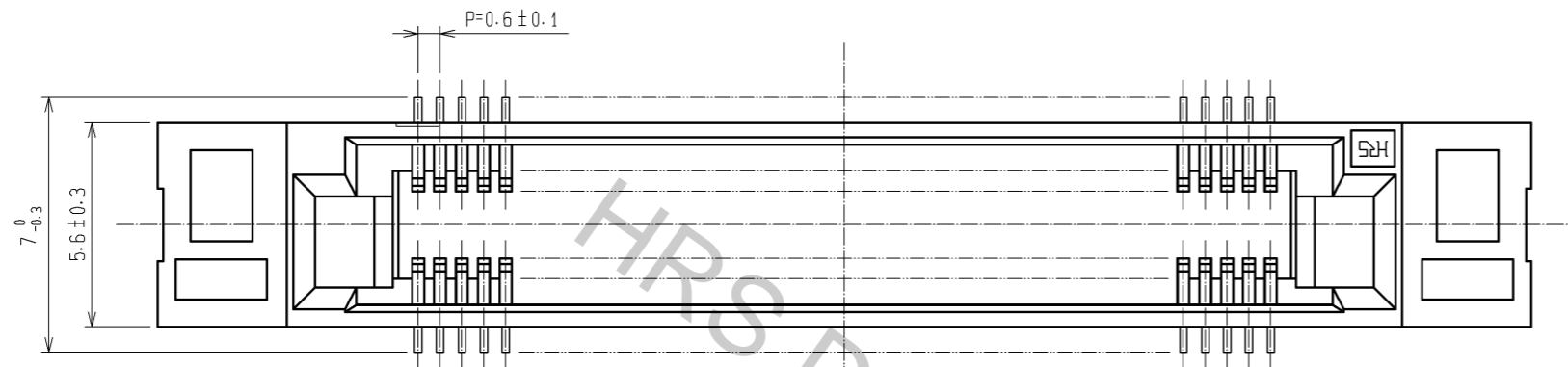
RECOMMENDED LAND PATTERN DIMENSION OF PCB (MOUNTING SIDE)  
(RECOMMENDED METAL MASK THICKNESS: 0.15mm)



- NOTES
- 1 LEAD CO-PLANARITY SHALL BE 0.1mm MAX.
  - 2 AFTER MOUNTING BOARD, REF. NO. 3 SHALL BE REMOVED.
  - 3 FOR MODIFICATION, ETC., PREVENTIVE HOLE FOR SINK MARK MAY BE ADDED DEPENDS ON CIRCUMSTANCES.
  - 4 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

1, 3	PPS	LIGHT BROWN (UL94V-0)	2	PHOSPHOR BRONZE	CONTACT AREA: GOLD 0.1µm min LEAD AREA: GOLD 0.03µm min UNDER PLATING: NICKEL 1.5µm min		
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS		
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
<b>HRS</b> HIROSE ELECTRIC CO., LTD.		APPROVED : HS. OKAWA	10.05.11	DRAWING NO. EDC3-150962-25			
		CHECKED : HT. YAMAGUCHI	10.05.11	PART NO. FX8C-80/80S11-SVJ(71)			
		DESIGNED : SY. KAMIGA	10.05.11	CODE NO. CL578-0903-2-71			
		DRAWN : HK. SUNADORI	10.05.11			1/2	

DETAIL AFTER REMOVING JOINT(5:1)



NOTE THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

<b>HRS</b>	DRAWING NO.	EDC3-150962-25
	PART NO.	FX8C-80/80S11-SVJ(C71)
	CODE NO.	CL578-0903-2-71
		$\triangle$ 2/2